

Day 1 - Monday 15th April 2024

18:30 Pre-conference networking drinks reception

Day 2 - Tuesday 16th April 2024

- 08:00 Registration and welcome refreshments
- 08:50 Housekeeping by Chris Meadows and Tim Bettles Conference Chairs

Ensuring SiC's phenomenal success

09:00	Silicon Carbide: a game changer in power electronics
09:15	Presented by Mario Saggio - STMicroelectronics Supporting SiC Success Stories Through Technical Innovation
09:30	Presented by David Liese - htt Group, and Michael Köppl - htt Group Next-Generation Factory Inspection: Improving Performance by Synthesizing Intelligent Microscopy
07.50	Presented by Marius Fischer - Nanotronics Challenges in HVM Amidst Evolving Device Architectures and Requirements for Compound Semiconductor based Power
09:45	Devices Presented by Nick Keller - Onto Innovation
10:00	Sharpening SiC Wafer specs and Frontend Performance by Crystal Orientation Metrology
10:15	Presented by Lars Grieger - Malvern Panalytical Sample preparation and TEM imaging techniques for advanced power device analysis
10:30	Presented by Antonio Mani - Thermo Fisher Scientific Morning Break
10.50	
11:10	Giving SiC a superjunction Presented by Reza Ghandi - GE Aerospace
11:25	The Unspoken Impacts of SiC Power Packaging Presented by Kevin Speer - Microchip
11:40	Challenges and solutions in new generation SiC metrology Presented by Dr. Eszter Najbauer - Semilab
11:55	Accelerating semiconductor technologies for the green revolution Presented by Shiva Rai - Applied Materials
12:10	A Hybrid Defect Inspection System for SiC substrate and Epi applications Presented by Aris Ma - AK Optics Technology Co. Ltd
12:25	Capital Efficient Systems for SiC Manufacturing Expansion and R&D Presented by Brian Stickney - C & D Semiconductor
12:40	Lunch Break
13:55	Enabling Low Cost SiC Boule Fabrication – The BoulePro 200AX is the New Process Of Record
14:10	Presented by Jeff Gum - Usach Industry ready detection of TSDs and BPDs in SiC wafers
14:25	Presented by DrIng. Christian Reimann - Rigaku Cutting-edge SiC Manufacturing: Beyond Chemical-Mechanical Constraints
14:40	Presented by Philipp Böttger - scia Systems GmbH Modernizing Industrial Low Voltage Motor Drives with Silicon Carbide
14.40	Presented by Pranjal Srivastava - Wolfspeed PulseForge and Teikoku Taping Systems Announce Novel Fully Automated Photonic Debonding Platform
14:55	Presented by Vahid Akhavan - PulseForge (in association with Teikoku Taping Systems Inc)
15:10	Coating at its best - Spraying graphite parts with tantalum carbide cuts the cost of producing SiC crystals
15.25	Presented by DrIng. Matthias Trempa - Fraunhofer IISB Powering the SiC Revolution with Vertical Integration
15:25	Presented by Ajay Poonjal Pai - Sanan
15:40	Afternoon Break
Taking po	ower from the photon
16:20	Record-breaking solar cells Presented by Dr. Oliver Höhn - Fraunhofer ISE
16:35	Integrated storage unlocks CPV's full potential Presented by Kira Rundel - RayGen
16:50	Germanium Substrates for Photonics and PV: Ensuring Supply Security, Advancing Recycling and Enabling CMOS integration Presented by Ivan Zyulkov - Umicore
17:05	Lattice-matched III-V solar cells. Progress and application opportunities Presented by Prof. Mircea Guina - Tampere University

- 17:20 Development of far-UVC LEDs for sensing and skin tolerant antisepsis *Presented by Sven Einfeldt - FBH Berlin*
 17:35 Heterogenous Integration of Compound Semiconductors by W2W and D2W Bonding *Presented by Dr. Bernd Dielacher - EV Group*
 17:50 Making monolithic RGB displays with InGaN *Presented by WonTaeg Lim - Soft-Epi*
- 18:05 Closing Remarks
- 18:10 Networking Drinks / Dinner Reception

Day 3 - Wednesday 17th April 2024

08:00 Registration and welcome refreshments

08:50 Housekeeping by Chris Meadows and Tim Bettles - Conference Chairs

Accelera	ating the growth of GaN Sponsored by Precision Fabricators
09:00	Where will GaN Power Semiconductors find their greatest success in the 2020s? Presented by Richard Eden - Omdia
09:15	The strengths of IC enhancement-mode GaN Presented by Andrea Bricconi - Cambridge GaN Devices
09:30	Presentation Title to be Confirmed
09:45	Harnessing the Power of RF GaN-on-Si Technology for Next Generation Connectivity <i>Presented by Nadine Collaert - imec</i>
10:00	Accelerating the Growth of GaN-based Power Electronics Via Adoption of 300mm Technology Presented by Rudy Parekh - Veeco
10:15	Next Level Epitaxy: Revolutionizing Mass Production of Wide Bandgap Semiconductors Presented by Dr. Yilmaz Dikme
10:30	Morning Break
11:10	Considerations for Tool-To-Tool Matching Across a Fleet of Metrology Tools Presented by Tamzin Lafford - Bruker UK
11:25	Connected metrology – Full 2D characterization of HEMT device structure epi-wafers <i>Presented by Johannes Zettler - LayTec AG</i>
11:40	Emerging Growth Opportunities for MBE in GaN Presented by Brian Miller - Riber
11:55	Commercialization of buffer-free GaN on SiC materials for defense, space, telecom markets and beyond <i>Presented by Jr-Tai Chen - SweGaN</i>
12:10	Numerical design propels RF and power GaN technology Presented by Ahmed Nejim - Silvaco
12:25	Solving the EMC and thermal issues of driving GaN at high speed Presented by Rupert Baines - QPT
12:40	GaN: Delivering on the Net-Zero Economics of an AI-Enabled Future Presented by Peter Rabbeni - IQE
12:55	Lunch Break
Expandi	ing horizons for surface emitters
14:10	VCSELs: Driving Innovations in 3D Sensing and Data Communication Presented by Ali Jaffal - Yole Group
14:25	Vertilas InP VCSELs to address fast growing and novel applications at and beyond 1.3 Im Presented by Christian Neumeyr - Vertilas
14:40	Expanding the scope of VCSELs through wavelength extension, added functionality and high power density <i>Presented by Julien Boucart - Coherent</i>
14:55	Speeding VCSEL feedback Presented by Jack Baker - ICS
15:10	Building, powerful, blue-surface-emitting SLEDs Presented by Juan Morales - iSLight
15:25	Novel high-power VCSEL laser modules for Battery Manufacturing Presented by Roman Koerner - TRUMPF
15:40	Placing photonic crystal nano-lasers to silicon Presented by Mingchu Tang - University College London
15.55	Closing Remarks

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